Count	Refdes	Value	Description	Size	Part Number	MFR
1	C4	C0805,2.2uf	CAP CER 2.2UF 50V 20% X7R 0402	0805	Std	Murata
1	C8	C0603,1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Murata
1	C10	C0805,1000pf	CAP CER 1000PF 250V 10% X7R 0805	0805	Std	TDK
1	C3	CAP_SC70_SERIES,470pF	CAP 470PF 250VAC CERAMIC Y1/X1		ECK-ANA471MB	Panasonic - ECG
3	C1 C9	6.8uF	CAP ALUM 6.8UF 400V 20% RADIAL	0.315 inch	UCS2G6R8MPD	Nichicon
1	C6	NA	CAP CER 470pF 100V 20% X7R 0603	0603	Std	Murata
1	D5	BAS20HT1G	Diode, Swithcing, 200 mA, 200V	SOD323	BAS20HT1G	Onsemi
1	D2	HD06	RECT BRIDGE GP 600V 0.8A MINIDIP	4-SMD	HD06	Diodes
1	D1	DFLR1600-7	DIODE STD REC 1A 600V POWERDI123	PowerDI™ 123	DFLR1600-7	Diodes
1	D4	SBR10U45SP5-13	DIODE BYPASS 10A 45V POWERDI5	PowerDI™ 5	SBR10U45SP5-13	Diodes
1	F2	RST 500AMMO	FUSE SLOW 250VAC 500MA RADIAL		RST 500AMMO	Bel Fuse Inc
1	C2 C7	270uf	CAP ALUM 270UF 6.3V 20% RADIAL	5*8mm	RF80J271MDN1PX	Nichicon
1	L1	1.5mH	I-inductor,1.5mH		7447462152	Wurth
1	R7	R0603,2.5k	Resistor, Chip, 1/16W, 1%	0603	STD	Yageo
1	R5	R0603,110k	Resistor, Chip, 1/16W, 1%	0603	STD	Yageo
1	R6	R0603,2k	Resistor, Chip, 1/16W, 1%	0603	STD	Yageo
1	R8	R0603,22k	Resistor, Chip, 1/16W, 1%	0603	STD	Yageo
1	R2	R0603,51	Resistor, Chip, 1/16W, 1%	0603	STD	Yageo
1	R1	R0603,DNP	Do Not Populate	0603	STD	Yageo
1	R4	R0805,1	Resistor, Chip, 1/8W, 1%	0805	STD	Yageo
1	R18	R1206,30K	Resistor, Chip, 1/4W, 1%,1206	1206	STD	Yageo
1	R3	R0805_1%,100	Resistor, Chip, 1/10W, 1%	0805	STD	Yageo
1	R9	R1206_1%,100K	Resistor, Chip, 1/4W, 1%	1206	STD	Yageo
2	R10-11	R0805_1%,7.5M	Resistor, Chip, 1/8W, 1%	0805	STD	Yageo

1	R15	NA	Resistor, Chip, 1/8W, 1%	0805	STD	Yageo
1	T1	RM6_2,RM6 480 uH	Transformer, Discontinuous Mode Flyback, ±7%		PG1284NL-MX2	Pulse
1	Q2	SPU04N60C3	MOSFET N-CH 650V 4.5A TO-251	Ipak	SPU04N60C3	Infineon
1	U2	UCC28700	Constant-Voltage, Constant-Current PWM With Primary-Side Regulation	6SOT-23	UCC28700	TI

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